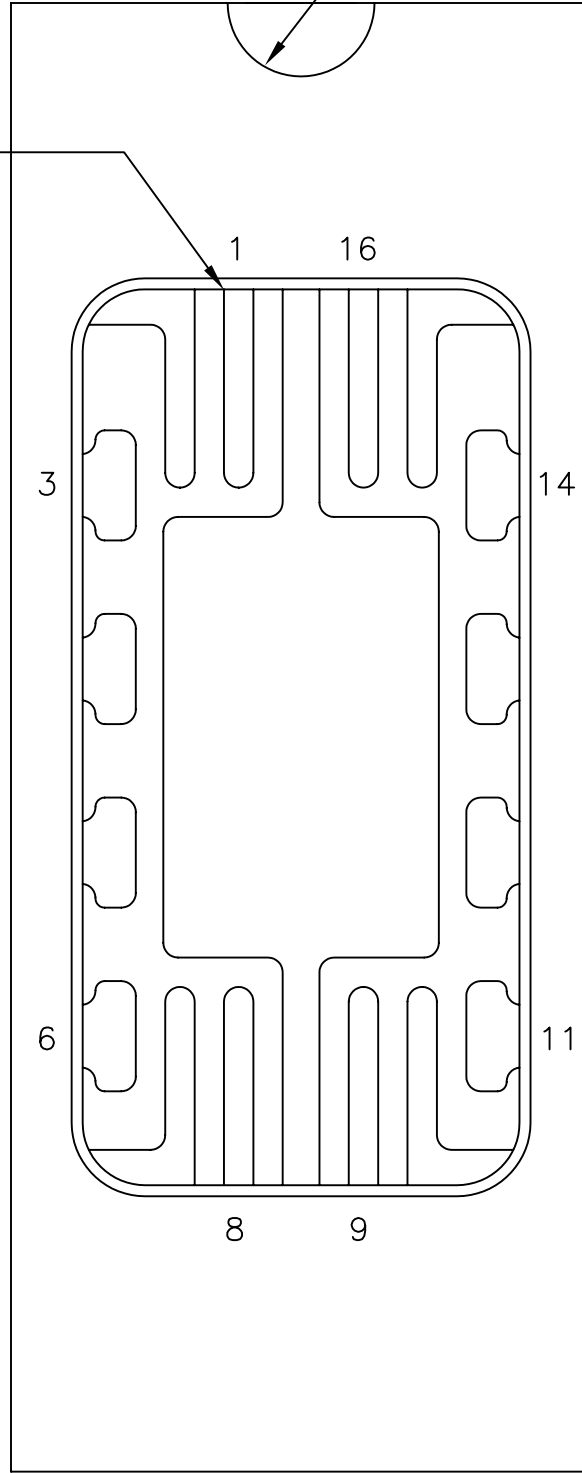




PIN #1 IDENTIFIER

BONDING PAD #1



DEVICE TYPE:				<b>SEMPAC, INC.</b> <b>Open-Pak™ Technologies</b> <a href="http://www.sempac.com">www.sempac.com</a> 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006					
CUSTOMER:		DIE SIZE:						16 Lead 150 mils SOIC Open-Pak Bonding Diagram	
WIRE TYPE/ SIZE:		NO. OF WIRES:							
THIRD ANGLE PROJECTION UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES DO NOT SCALE DRAWING	REVISIONS					SIZE <b>A</b> PART NO. <b>SOIC150-16-OP-01</b> REV <b>2</b>			
	ECN NO.	DATE	DESCRIPTION	APPROVED					
	10510	11/2/05	PRODUCTION RELEASE	D.BENANDO					
DRAWN BY	W. GRIFFITTS	DATE	11/1/05	PACKAGE SIZE:	0.400" x 0.158"	SCALE	20X		
APP BY	P. FLASKERUD	DATE	11/1/05	DIE PAD SIZE:	0.120" x 0.075"	CAD FILE	SOIC150-16-OP-01-R2.DWG		
						SHEET	1 OF 1		

